

L Number	Hits	Search Text	DB	Time stamp
1	44	((mass near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) with (before or prior) with (exposur\$3 or lithograph\$6 or photomask\$3 or photo-mask\$3 or mask\$3 or resist or photo-resist or photolithograph\$6 or stepper or photo-lithograph\$6)) and (photomask\$3 or photo-mask\$3 or photoresist or photo-resist or ((mask\$3 or resist) with (photo or EUV or UV or ultra-violet or light or DUV or excimer or lightsource or photolithograph\$6 or photosensit\$6 or photo-lithograph\$6 or positive or negative)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 10:30
2	56	(mass near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) with (deposit\$4 or anneal\$5).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 07:19
3	333	(mass near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) with (deposit\$4 or anneal\$5) with (advantag\$5 or cost)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 07:20
4	326	(mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) with (deposit\$4 or anneal\$5) with (advantag\$5 or cost)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 10:31
5	349136	700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 12:00
6	59	((mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) with (deposit\$4 or anneal\$5) with (advantag\$5 or cost)) and (700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 07:21
20	24121	(photomask\$3 or photo-mask\$3 or mask\$3) near3 (type or kind or class)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 10:31
21	1577	(photomask\$3 or photo-mask\$3 or mask\$3) near3 (type or kind or class).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 10:58
22	873	(700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls.) and ((photomask\$3 or photo-mask\$3 or mask\$3) near3 (type or kind or class).clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 10:31
23	473141	(mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) or batch or lot	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 10:32
24	89	((700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls.) and ((photomask\$3 or photo-mask\$3 or mask\$3) near3 (type or kind or class).clm.)) and ((mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) or batch or lot)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 10:40

25	1063	257/390.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 10:40
26	58	257/390.ccls. and (organic or polymer or resin or polyimide or phenolic or acrylic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 10:42
27	25472	(photomask\$3 or photo-mask\$3 or mask\$3) near3 (type or kind or class or (metal and (organic or polymer or resin or polyimide or phenolic or acrylic)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 10:59
28	7786	(photomask\$3 or photo-mask\$3 or mask\$3) with (metal and (organic or polymer or resin or polyimide or phenolic or acrylic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 12:04
29	307	((photomask\$3 or photo-mask\$3 or mask\$3) near3 (type or kind or class or (metal and (organic or polymer or resin or polyimide or phenolic or acrylic)))) and (345/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 11:00
30	59	((photomask\$3 or photo-mask\$3 or mask\$3) with (metal and (organic or polymer or resin or polyimide or phenolic or acrylic))) and (345/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 11:00
31	1	(photomask\$3 or photo-mask\$3 or mask\$3) with (metal and (organic or polymer or resin or polyimide or phenolic or acrylic)) with menu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 12:31
41	8	3767490.URPN.	USPAT	2004/09/17 11:23
45	48	216/49.ccls. and 216/51.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 11:59
46	1061	exposure with (ebeam or e-beam)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 11:59
47	3002	exposure with (ebeam or e-beam or (energy near2 beam))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 12:31
48	361865	700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 12:01
49	556111	700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 13:54

50	303	382/144.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 12:03
51	20	382/144.ccls. and (organic or polymer or resin or polyimide or phenolic or acrylic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 13:00
52	556260	(700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.) or 382/144.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 12:31
53	1304	((700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.) or 382/144.ccls.) and (exposure with (ebeam or e-beam or (energy near2 beam)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 12:31
54	77	((700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.) or 382/144.ccls.) and (exposure with (ebeam or e-beam or (energy near2 beam)))) and ((photomask\$3 or photo-mask\$3 or mask\$3) with (metal and (organic or polymer or resin or polyimide or phenolic or acrylic)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 12:58
55	318	((photomask\$3 or photo-mask\$3) near3 ((first and second) or another)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 13:50
56	261	((700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.) or 382/144.ccls.) and (((photomask\$3 or photo-mask\$3) near3 ((first and second) or another)).clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 12:59
57	82	((700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.) or 382/144.ccls.) and (((photomask\$3 or photo-mask\$3) near3 ((first and second) or another)).clm.)) and (organic or resin or polyimide or phenolic or acrylic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 13:51
58	2818	(photomask\$3 or photo-mask\$3 or mask\$3) with ((mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) or batch or lot)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 13:54
59	286006	((organic or resin or polyimide or phenolic or acrylic) with (photosensit\$5 or photolacquer or photo-lacquer or photo-lithograph\$6 or photolithograph\$6 or expos\$4 or radiation or UV or EUV or shield\$4 or block\$4 or sheild\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:35
60	310	(photomask\$3 or photo-mask\$3 or mask\$3) with (before or prior or subsequent or after) with ((mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) or batch or lot)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 14:22
61	33	((organic or resin or polyimide or phenolic or acrylic) with (photosensit\$5 or photolacquer or photo-lacquer or photo-lithograph\$6 or photolithograph\$6 or expos\$4 or radiation or UV or EUV or shield\$4 or block\$4 or sheild\$4))) and ((photomask\$3 or photo-mask\$3 or mask\$3) with (before or prior or subsequent or after) with ((mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) or batch or lot))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 14:03

62	14	((700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.) or 382/144.ccls.) and (((organic or resin or polyimide or phenolic or acrylic) with (photosensit\$5 or photolacquer or photo-lacquer or photo-lithograph\$6 or photolithograph\$6 or expos\$4 or radiation or UV or EUV or shield\$4 or block\$4 or sheild\$4))) and ((photomask\$3 or photo-mask\$3 or mask\$3) with (before or prior or subsequent or after) with ((mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) or batch or lot)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 13:54
63	19	(((organic or resin or polyimide or phenolic or acrylic) with (photosensit\$5 or photolacquer or photo-lacquer or photo-lithograph\$6 or photolithograph\$6 or expos\$4 or radiation or UV or EUV or shield\$4 or block\$4 or sheild\$4))) and ((photomask\$3 or photo-mask\$3 or mask\$3) with (before or prior or subsequent or after) with ((mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) or batch or lot))) not (((700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.) or 382/144.ccls.) and (((organic or resin or polyimide or phenolic or acrylic) with (photosensit\$5 or photolacquer or photo-lacquer or photo-lithograph\$6 or photolithograph\$6 or expos\$4 or radiation or UV or EUV or shield\$4 or block\$4 or sheild\$4))) and ((photomask\$3 or photo-mask\$3 or mask\$3) with (before or prior or subsequent or after) with ((mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) or batch or lot))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 14:14
65	273	(photomask\$3 or photo-mask\$3 or mask\$3) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:27
66	1119	(photomask\$3 or photo-mask\$3 or mask\$3) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:33
68	1374	((photomask\$3 or photo-mask\$3 or mask\$3) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making))) or ((photomask\$3 or photo-mask\$3 or mask\$3) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 14:26
69	181	(((organic or resin or polyimide or phenolic or acrylic) with (photosensit\$5 or photolacquer or photo-lacquer or photo-lithograph\$6 or photolithograph\$6 or expos\$4 or radiation or UV or EUV or shield\$4 or block\$4 or sheild\$4))) and (((photomask\$3 or photo-mask\$3 or mask\$3) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making))) or ((photomask\$3 or photo-mask\$3 or mask\$3) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 14:37
70	91	((700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.) or 382/144.ccls.) and (((organic or resin or polyimide or phenolic or acrylic) with (photosensit\$5 or photolacquer or photo-lacquer or photo-lithograph\$6 or photolithograph\$6 or expos\$4 or radiation or UV or EUV or shield\$4 or block\$4 or sheild\$4))) and (((photomask\$3 or photo-mask\$3 or mask\$3) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making))) or ((photomask\$3 or photo-mask\$3 or mask\$3) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 14:37
71	321694	((organic or resin or polyimide or phenolic or acrylic) with (photosensit\$5 or photolacquer or photo-lacquer or photo-lithograph\$6 or photolithograph\$6 or light or UV or EUV or shield\$4 or block\$4 or sheild\$4 or phototool\$3 or photo-tool\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:34

72	172	((((organic or resin or polyimide or phenolic or acrylic) with (photosensit\$5 or photolacquer or photo-lacquer or photo-lithograph\$6 or photolithograph\$6 or light or UV or EUV or shield\$4 or block\$4 or sheild\$4 or phototool\$3 or photo-tool\$3))) and (((photomask\$3 or photo-mask\$3 or mask\$3) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making))) or ((photomask\$3 or photo-mask\$3 or mask\$3) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making))))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 14:37
73	81	((700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.) or 382/144.ccls.) and (((((organic or resin or polyimide or phenolic or acrylic) with (photosensit\$5 or photolacquer or photo-lacquer or photo-lithograph\$6 or photolithograph\$6 or light or UV or EUV or shield\$4 or block\$4 or sheild\$4 or phototool\$3 or photo-tool\$3))) and (((photomask\$3 or photo-mask\$3 or mask\$3) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making))) or ((photomask\$3 or photo-mask\$3 or mask\$3) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or making))))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 14:37
74	2	20020042007.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:21
76	5033	(before or prior or subsequent\$2) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:45
77	5007	(before or prior or subsequent\$2) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:44
78	10005	((before or prior or subsequent\$2) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3))) or ((before or prior or subsequent\$2) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:34
79	3	((((before or prior or subsequent\$2) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3))) or ((before or prior or subsequent\$2) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)))) and ((organic or resin or polyimide or phenolic or acrylic) with (photomask\$3 or photo-mask\$3) with (block\$4 or sheild\$3 or attenuat\$4 or absorb\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:46
80	23	((((before or prior or subsequent\$2) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3))) or ((before or prior or subsequent\$2) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)))) and ((organic or resin or polyimide or phenolic or acrylic) with mask\$3 with (photosensit\$5 or photolacquer or photo-lacquer or photo-lithograph\$6 or photolithograph\$6 or UV or EUV or shield\$4 or block\$4 or sheild\$4 or attenuat\$4 or absorb\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:39
81	51	(before or prior or subsequent\$2) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:45
82	42	(before or prior or subsequent\$2) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:45

83	93	((before or prior or subsequent\$2) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist)) or ((before or prior or subsequent\$2) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:45
84	23	((before or prior or subsequent\$2) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist)) or ((before or prior or subsequent\$2) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist))) and (organic or resin or polyimide or phenolic or acrylic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:46
85	14	((before or prior or subsequent\$2) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist)) or ((before or prior or subsequent\$2) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist))) and (organic or resin or polyimide or phenolic or acrylic)) and ((700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.) or 382/144.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:51
86	0	((before or prior or subsequent\$2) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist)) or ((before or prior or subsequent\$2) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist))) and (organic or resin or polyimide or phenolic or acrylic)) and ((700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.) or 382/144.ccls.) not (((before or prior or subsequent\$2) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist)) or ((before or prior or subsequent\$2) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist))) and (organic or resin or polyimide or phenolic or acrylic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:51
87	9	((before or prior or subsequent\$2) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist)) or ((before or prior or subsequent\$2) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist))) and (organic or resin or polyimide or phenolic or acrylic)) not (((before or prior or subsequent\$2) with (mass adj2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist)) or ((before or prior or subsequent\$2) with ((batch or lot) near2 (produc\$4 or manufactur\$4 or fabricat\$4 or process\$3)) with (photomask\$3 or photo-mask\$3 or mask\$3 or photoresist or photo-resist))) and (organic or resin or polyimide or phenolic or acrylic)) and ((700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls. or 216/\$.ccls. or 257/\$.ccls.) or 382/144.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 15:51
-	1	20020042007.pn. and Rom and logic and cell	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 20:30
-	1	20020042007.pn. and Rom and logic and (unit near2 cell)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 20:54

-	1	20020042007.pn. and photomask\$3 with amount	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 20:54
-	1	20020042007.pn. and (photomask\$3 with amount)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 20:55
-	1	20020042007.pn. and (exposur\$3 with amount)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 21:03
-	1	20020042007.pn. and ((exposur\$3 or photomask\$3) with (amount or judg\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 21:04
-	1	20020042007.pn. and ((exposur\$3 or photomask\$3) with (amount or judg\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 21:04
-	1	20020042007.pn. and ((exposur\$3 or photomask\$3) same (amount or judg\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 22:18
-	1	20020042007.pn. and (prior).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 21:52
-	1	20020042007.pn. and (prior)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 21:52
-	1	20020042007.pn. and (pattern\$4 with logic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 22:20
-	1	20020042007.pn. and (pattern\$4 same logic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 22:24
-	1	20020042007.pn. and (pattern\$4 same ROM)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 22:26
-	1	20020042007.pn. and (menu same type)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 22:26

-	1	20020042007.pn. and (energy near3 beam)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 22:27
-	1	20020042007.pn. and (evaluat\$4 same predetermin\$7 same pattern\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 22:30
-	1	20020042007.pn. and (reproduc\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 22:29
-	1	20020042007.pn. and (differ\$8 same region\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 22:29
-	1	20020042007.pn. and (evaluat\$4 same quality same pattern\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 22:30
-	2	20020042007.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 22:38
-	1	20020042007.pn. and mass.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 23:01
-	1	20020042007.pn. and prior	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 23:08
-	3736	ROM near3 logic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 23:08
-	2193	ROM near2 logic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 23:10
-	463	ROM near2 (logic near2 circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 23:10
-	1	20020042007.pn. and (product\$4 near4 amount)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 01:15

-	2	20020042007.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/15 23:33
-	684	organic with (photomask\$3 or photo-mask\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:24
-	700	(mass near2 production) with (exposure or lithography)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:36
-	5	((mass near2 production) with (exposure or lithography)) and (700/121.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:26
-	355	organic\$4 with (photomask\$3 or photo-mask\$3 or mask\$3) with resin with (photo or EUV or UV or ultra-violet or light or lightsource or photolithograph\$6 or photosensit\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:52
-	1	(organic\$4 with (photomask\$3 or photo-mask\$3 or mask\$3) with resin with (photo or EUV or UV or ultra-violet or light or lightsource or photolithograph\$6 or photosensit\$6)) and (700/121.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:48
-	138	(organic\$4 with (photomask\$3 or photo-mask\$3 or mask\$3) with resin with (photo or EUV or UV or ultra-violet or light or lightsource or photolithograph\$6 or photosensit\$6)) and (700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:34
-	1936	(mass near2 production) with (exposure or lithography or photomask\$3 or photo-mask\$3 or mask\$3 or resist or photo-resist or photolithograph\$6 or stepper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:42
-	4	((organic\$4 with (photomask\$3 or photo-mask\$3 or mask\$3) with resin with (photo or EUV or UV or ultra-violet or light or lightsource or photolithograph\$6 or photosensit\$6)) and (700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls.)) and ((mass near2 production) with (exposure or lithography or photomask\$3 or photo-mask\$3 or mask\$3 or resist or photo-resist or photolithograph\$6 or stepper))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:46
-	2805	(mass near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) with (exposure or lithograph\$6 or photomask\$3 or photo-mask\$3 or mask\$3 or resist or photo-resist or photolithograph\$6 or stepper or photo-lithograph\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:46
-	2806	(mass near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) with (exposur\$3 or lithograph\$6 or photomask\$3 or photo-mask\$3 or mask\$3 or resist or photo-resist or photolithograph\$6 or stepper or photo-lithograph\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:52
-	8	((organic\$4 with (photomask\$3 or photo-mask\$3 or mask\$3) with resin with (photo or EUV or UV or ultra-violet or light or lightsource or photolithograph\$6 or photosensit\$6)) and (700/\$.ccls. or 702/\$.ccls. or 438/\$.ccls. or 716/\$.ccls. or 430/\$.ccls.)) and ((mass near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) with (exposur\$3 or lithograph\$6 or photomask\$3 or photo-mask\$3 or mask\$3 or resist or photo-resist or photolithograph\$6 or stepper or photo-lithograph\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:46

-	13	((mass near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) with (exposur\$3 or lithograph\$6 or photomask\$3 or photo-mask\$3 or mask\$3 or resist or photo-resist or photolithograph\$6 or stepper or photo-lithograph\$6)) and (700/121.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:48
-	76	(mass near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) with (before or prior) with (exposur\$3 or lithograph\$6 or photomask\$3 or photo-mask\$3 or mask\$3 or resist or photo-resist or photolithograph\$6 or stepper or photo-lithograph\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 00:56
-	276315	photomask\$3 or photo-mask\$3 or photoresist or photo-resist or ((mask\$3 or resist) with (photo or EUV or UV or ultra-violet or light or DUV or excimer or lightsource or photolithograph\$6 or photosensit\$6 or photo-lithograph\$6 or positive or negative))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 01:31
-	2	20020042007.pn. and (organic\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 01:17
-	9	("4684971" "5376483" "5378585" "5389474" "5418092" "5556724" "5741613" "5989760" "5948572").pn.	USPAT	2004/09/16 01:18
-	2110	((resist with (photo or EUV or UV or ultra-violet or light or DUV or excimer or lightsource or photolithograph\$6 or photosensit\$6 or photo-lithograph\$6 or positive or negative)) or photoresist) with organic\$4 with resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 01:32
-	107	((((resist with (photo or EUV or UV or ultra-violet or light or DUV or excimer or lightsource or photolithograph\$6 or photosensit\$6 or photo-lithograph\$6 or positive or negative)) or photoresist) with organic\$4 with resin) and @py<1985	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 01:39
-	228	((((resist with (photo or EUV or UV or ultra-violet or light or DUV or excimer or lightsource or photolithograph\$6 or photosensit\$6 or photo-lithograph\$6 or positive or negative)) or photoresist) with organic\$4 with resin).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 01:33
-	14	(((((resist with (photo or EUV or UV or ultra-violet or light or DUV or excimer or lightsource or photolithograph\$6 or photosensit\$6 or photo-lithograph\$6 or positive or negative)) or photoresist) with organic\$4 with resin) and @py<1985) and (((((resist with (photo or EUV or UV or ultra-violet or light or DUV or excimer or lightsource or photolithograph\$6 or photosensit\$6 or photo-lithograph\$6 or positive or negative)) or photoresist) with organic\$4 with resin).clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 01:38
-	4649	photoresist near2 metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 01:39
-	680	(photoresist near2 metal).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 01:39
-	75	((photoresist near2 metal).clm.) and @py<1985	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 14:41

-	0	20020042007.pn. and (Rom same logic same cell)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 19:26
-	1	5965306.pn. and (mass with production)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 20:44
-	2	5965306.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 20:44
-	2241	(mass near2 (produc\$4 or manufactur\$4 or fabricat\$4 or making)) with (deposit\$4 or anneal\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/16 21:26